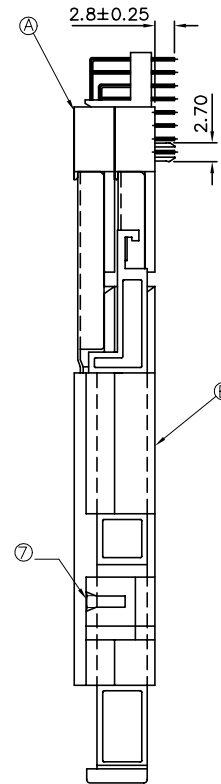
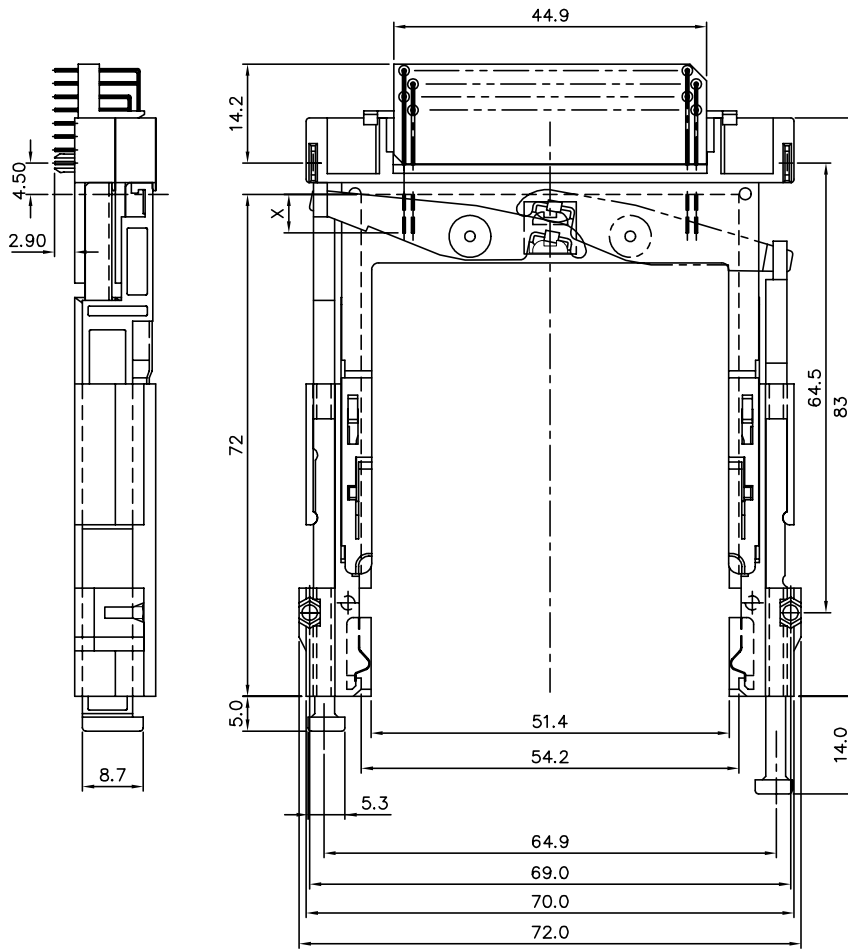


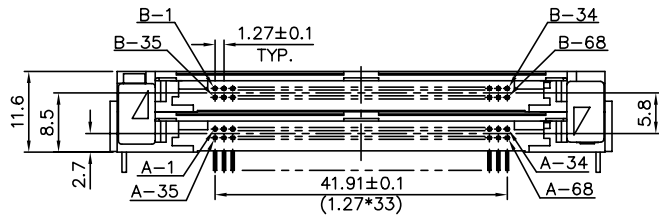
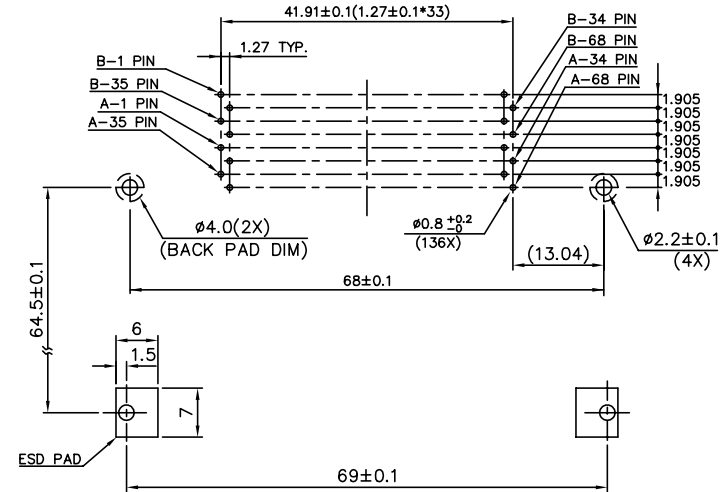
PRODUCT NO.
94721-001CA/001CALF



NOTES:

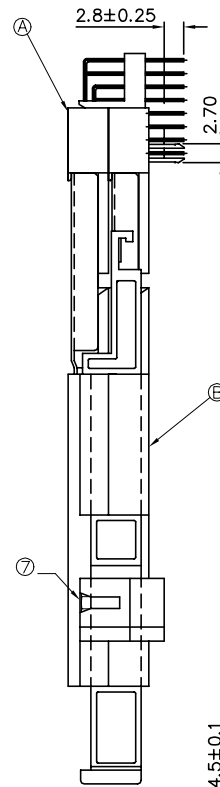
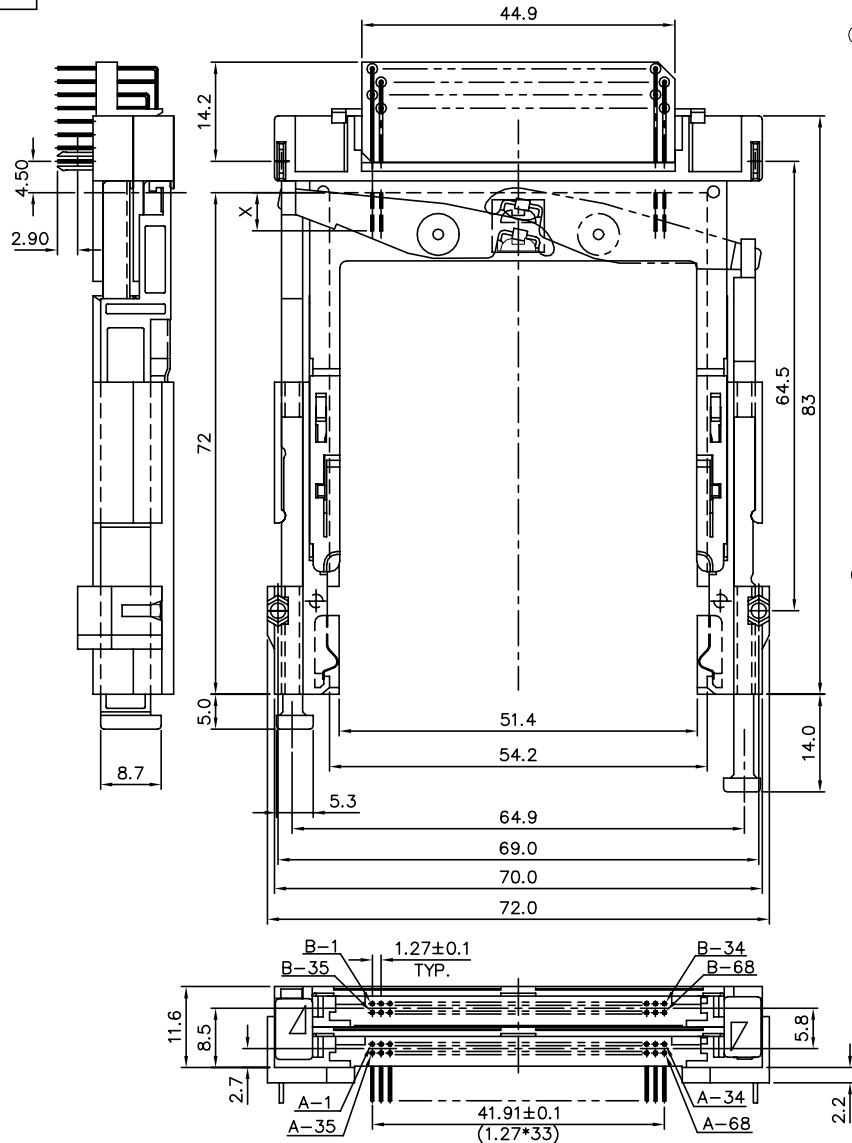
1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. Ni
 - CONTACT AREA : 0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302 ✓	tolerance ISO406 ISO1101	projection MM	product family PCMCIA
ltr ecn nodr	date	tolerances unless otherwise specified	scale 1.5:1	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
K N05-174 WB	06/16/05	angle 0°	MM	dwg no
L BX-N-007963 ZK	11/01/11	0°±2'	MM	sheet 1 of 12
M BX-N-011435 ZK	04/23/12	0°±2'	MM	size A4
F T50218 WL	0726/95	dr C L FENG	04/06/94	FCI logo
G T50236 WL	0815/95	engr JOSEPH HSIA	04/06/94	94721
H T60040 WL	01/30/96	chr JOSEPH HSIA	04/06/94	type Product Customer Drawing
J T60486 WL	12/09/96	app D K WANG	04/06/94	
sheet index	revision	M M M M M M M M M M M M M M		
	sheet	1 2 3 4 5 6 7 8 9 10 11 12		

PRODUCT NO.
94721-002CA/002CALF

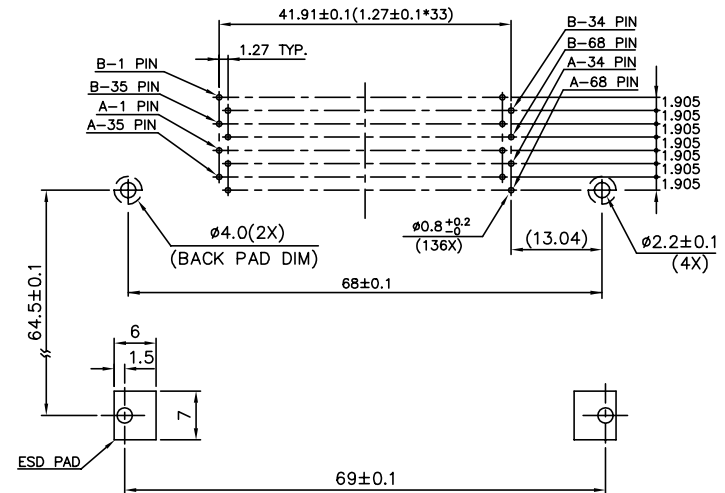


NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
 - TO MOUNT PART ④ ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART ⑤ WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART ④ (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - PART ⑤ (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
- FINISH (PIN)
UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)

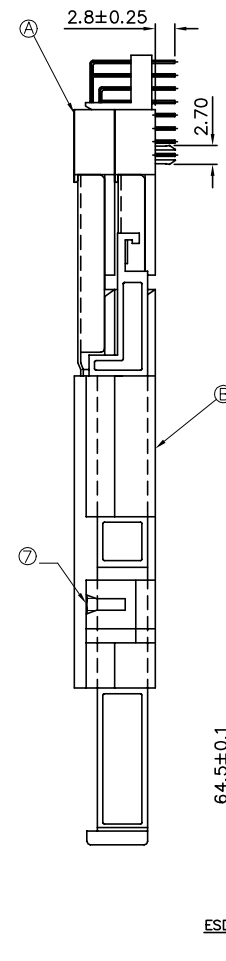
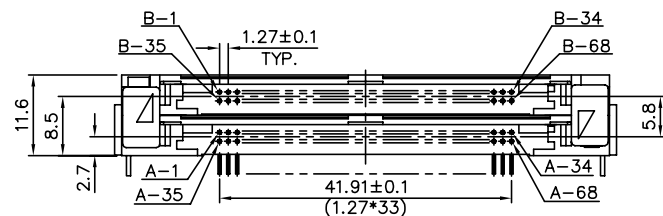
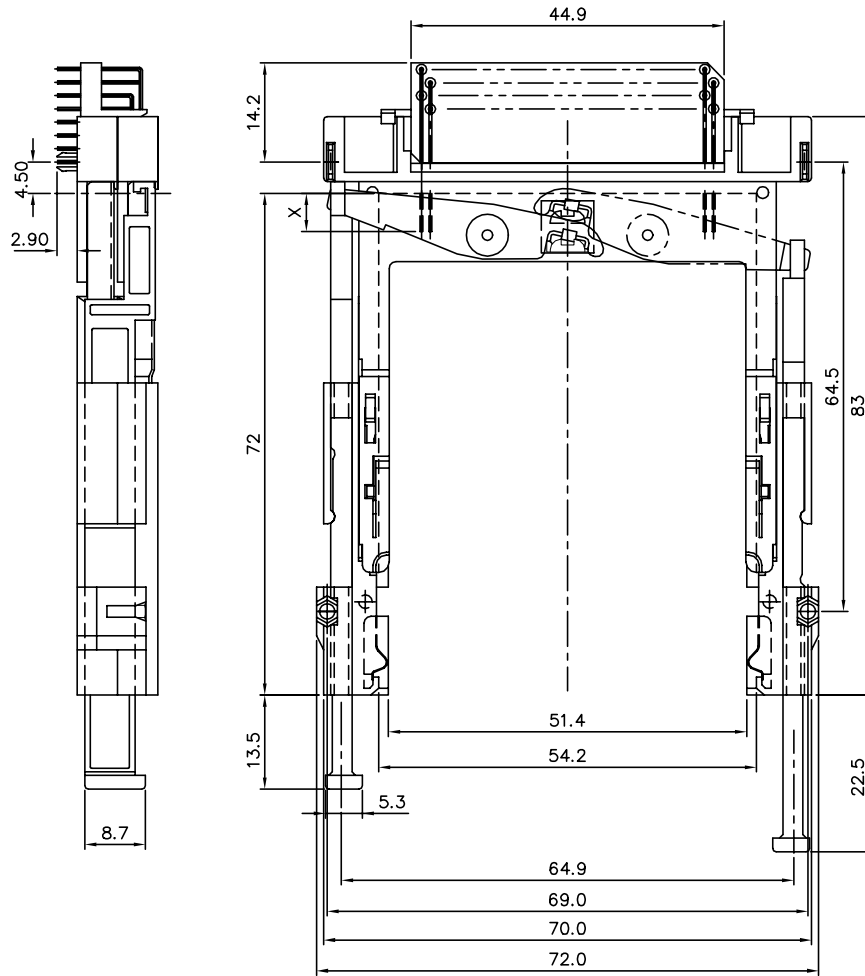
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
trnecn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle 0°±2'	0.X±0.3 0.XX±0.13 0.XXX±0.05	scale:1.5:1	dwg no 94721 sheet 2 of 12 size A4
dr c L FENG 04/06/94				type Product Customer Drawing
engr JOSEPH HSIA 04/06/94				
chr JOSEPH HSIA 04/06/94				
appd D K WANG 04/06/94				
sheet index	revision sheet			

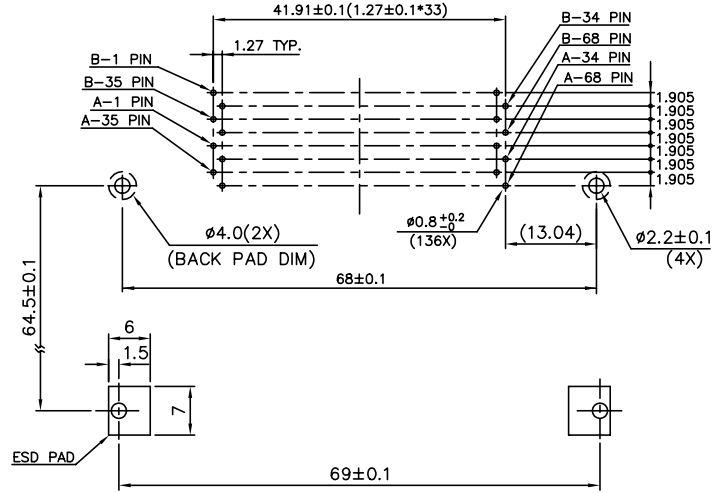
PRODUCT NO.
94721-001DA/001DALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
 - ASSY PROCESS
 - TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART B WITH TWO SCREWS.
 - EJECT TRAVEL: 9.0mm
 - MATERIAL
 - PART A (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - PART B (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
 - FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -****LF)

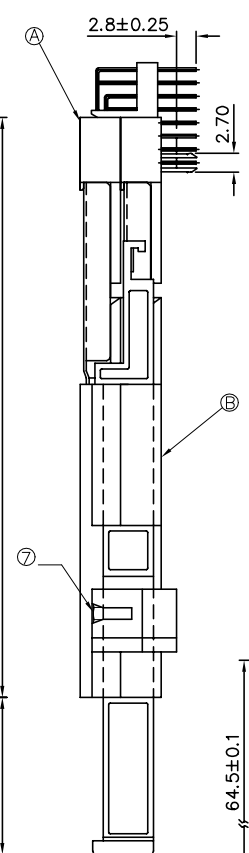
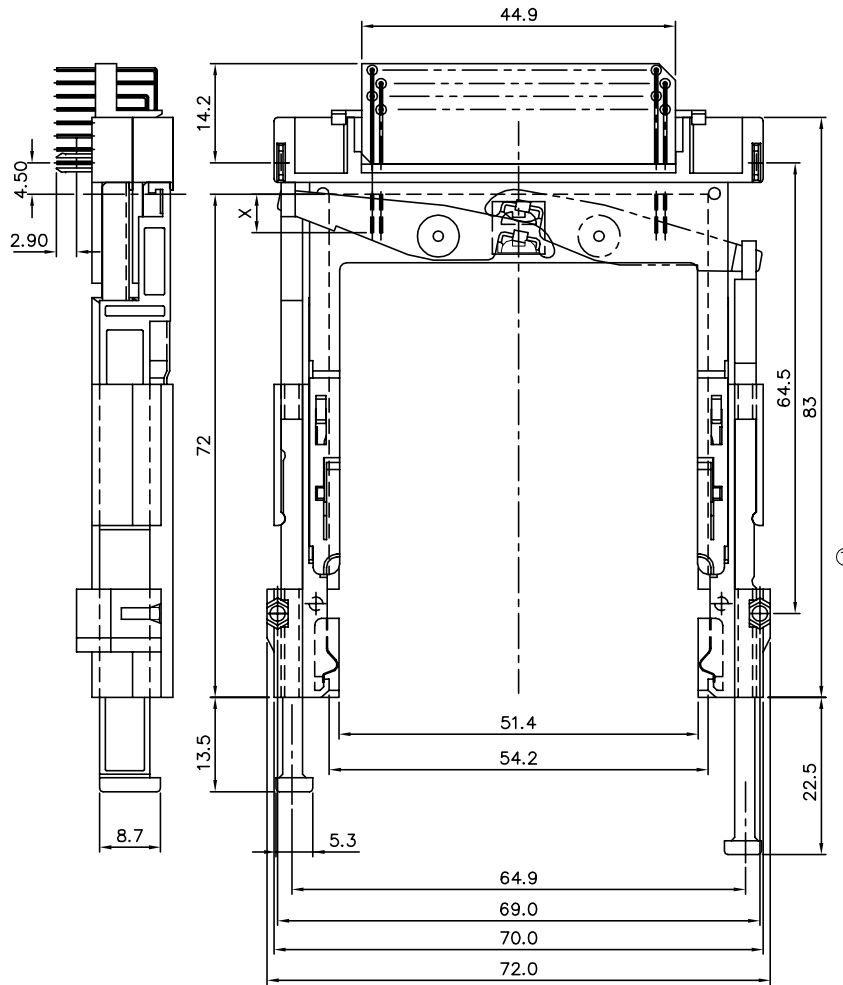
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l'recn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale:1.5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 3 of 12 size A4
	dr c L FENG	0.XXX±0.05		type Product Customer Drawing
	eng JOSEPH HSIA	04/06/94		
	chr JOSEPH HSIA	04/06/94		
	app D K WANG	04/06/94		
sheet index	revision sheet			

PRODUCT NO.
94721-002DA/002DALF

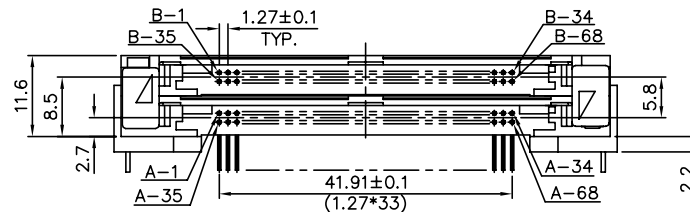
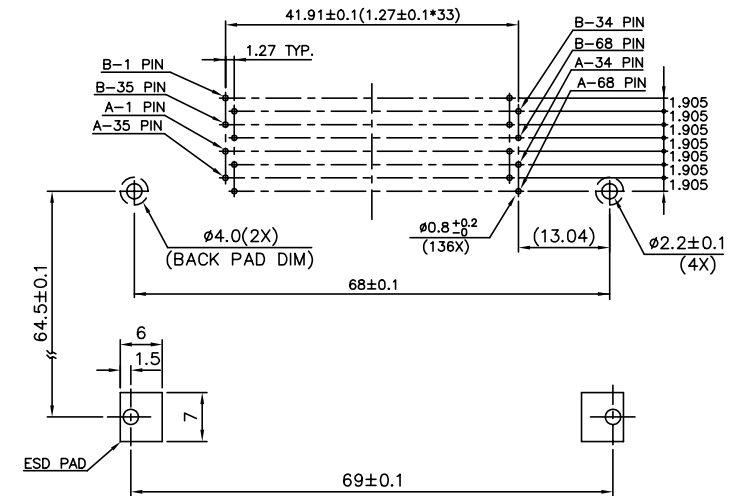


NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
 - TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2) AND SOLDER THEN FIX PART B WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART A (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - PART B (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -*****LF)

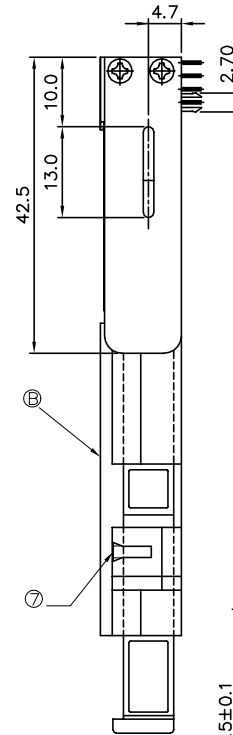
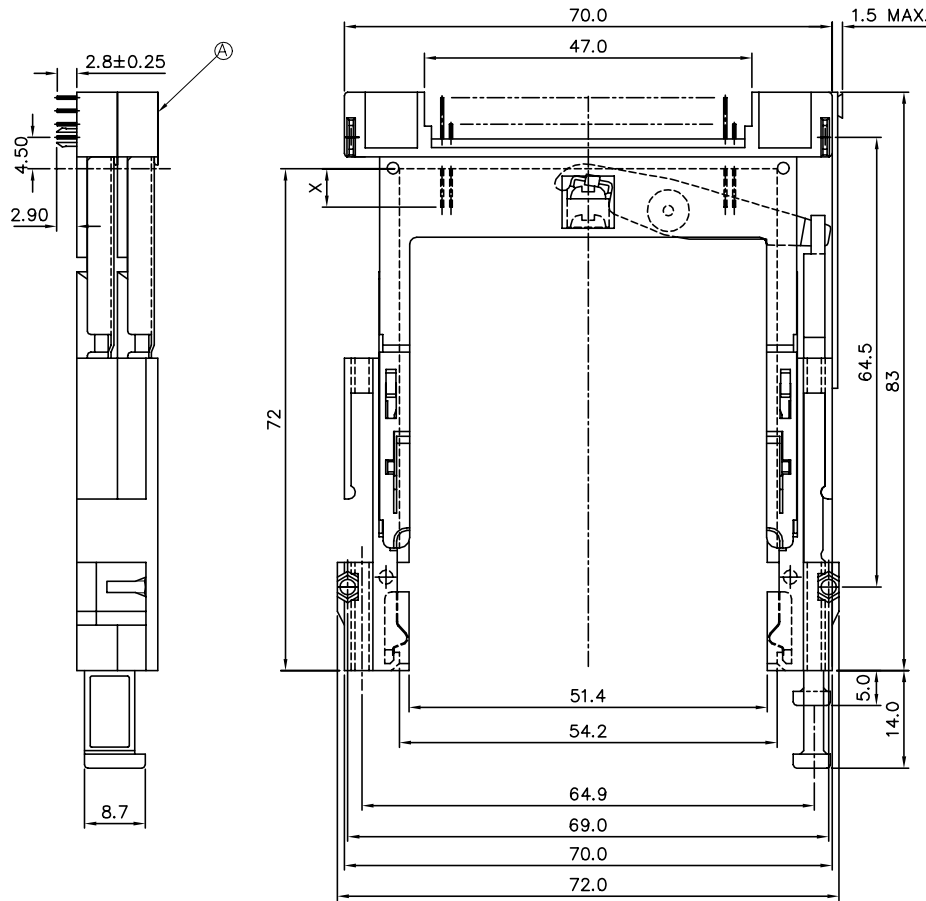
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface ISD1302	tolerance ISD406 ISD1101	projection	product family PCMCIA
ltr ecn nodr date	tolerances unless otherw	spec	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3	
M	angle	0.X±0.3	MM	
	0°±2'	0.XX±0.13	scale 1.5:1	
	dr	C L FENG 04/06/94	FCI	dwg no
	eng	JOSEPH HSIA 04/06/94		sheet 4 of 12
	chr	JOSEPH HSIA 04/06/94		size 94721 A4
	app	D K WANG 04/06/94		type Product Customer Drawing
sheet index	revision sheet			

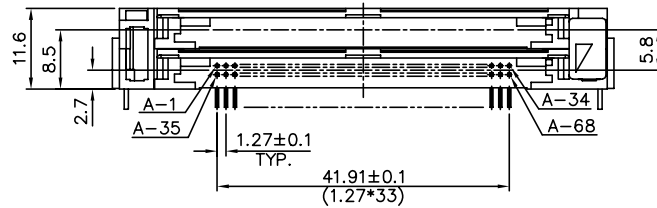
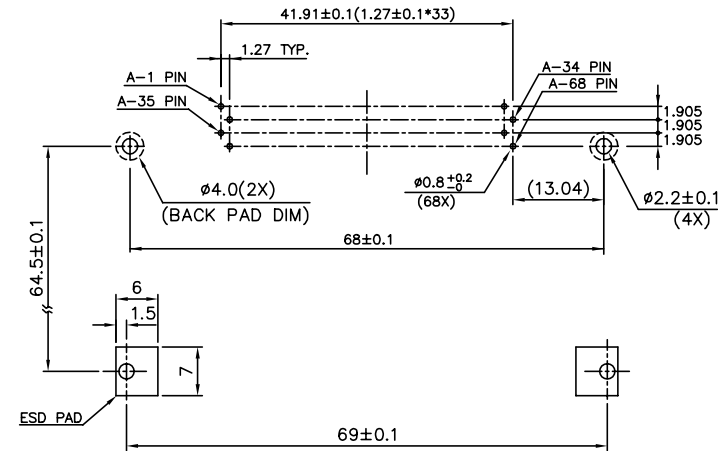
PRODUCT NO.
94721-003CA/003CALF



NOTES:

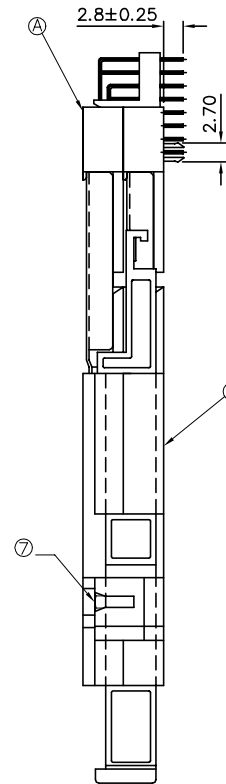
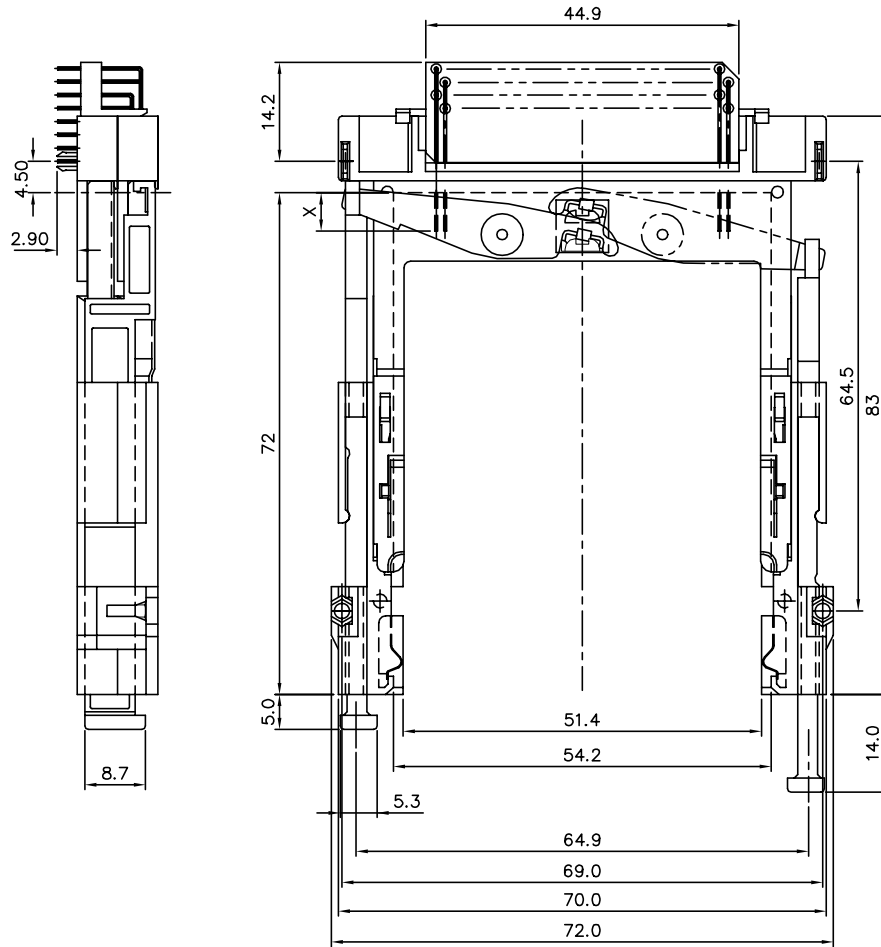
1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
- (A) MATERIAL
- 4.1 PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
- 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
: 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- (B) NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l'tecn nodr date	tolerances unless otherwise specified	angle 0°±2'	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	scale:5:1	dr c L FENG 04/06/94	FCI	dwg no 94721 sheet 5 of 12 size A4
		engr JOSEPH HSIA 04/06/94		type Product Customer Drawing
		chr JOSEPH HSIA 04/06/94		
		app'd D K WANG 04/06/94		
sheet index	revision sheet			

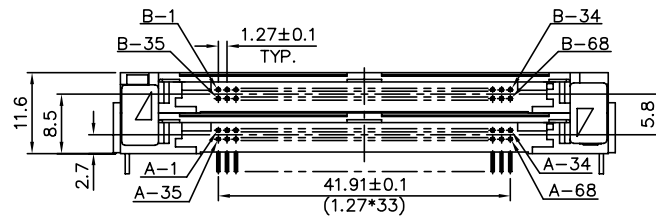
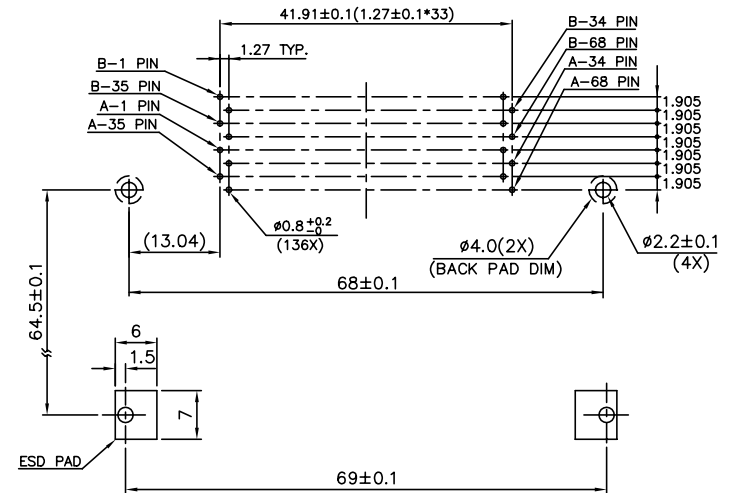
PRODUCT NO.
94721-004CA/004CALF



NOTES:

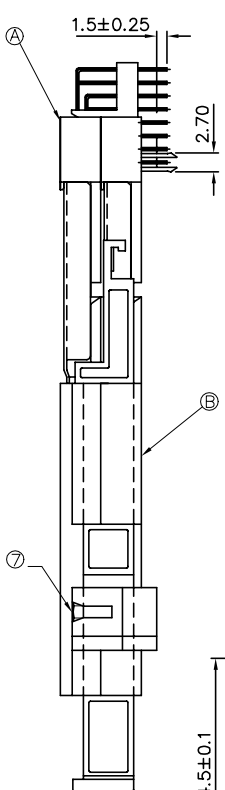
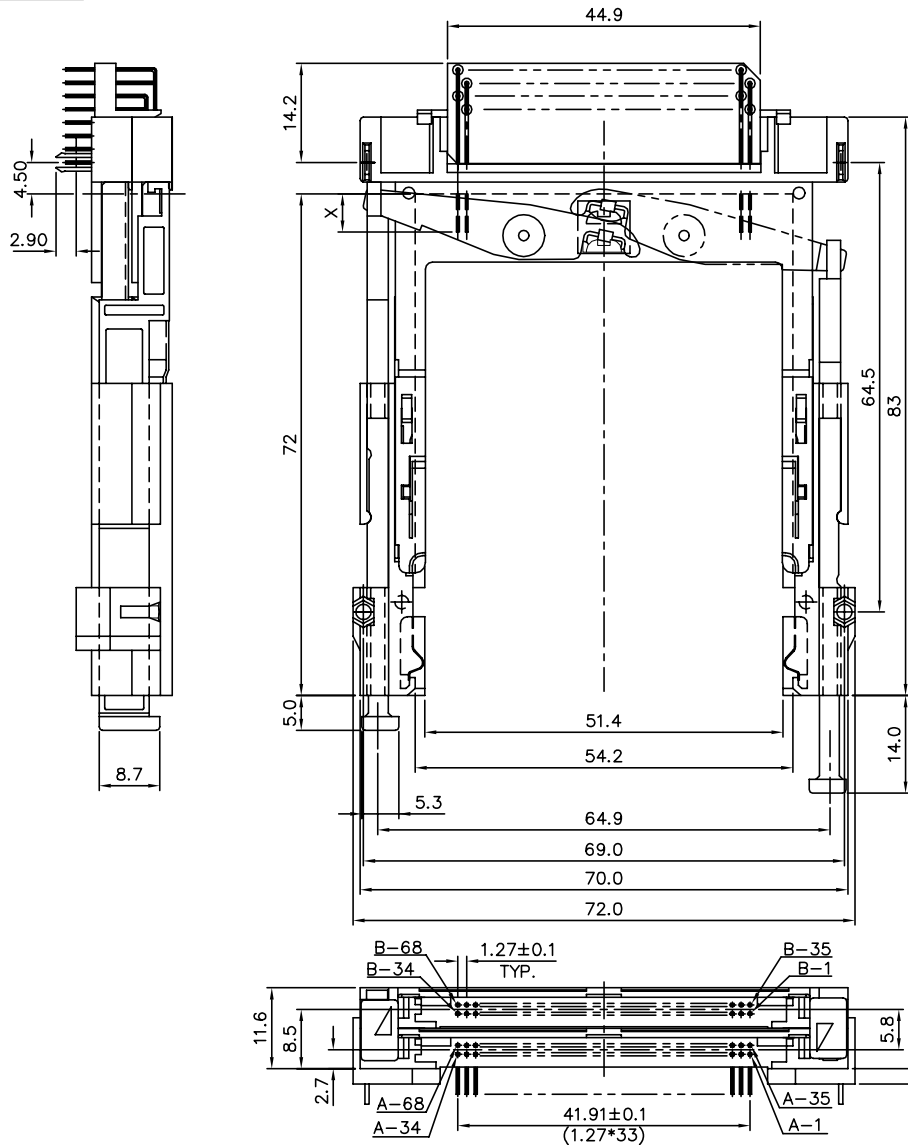
1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART Ⓐ ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART Ⓑ WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
- Ⓐ MATERIAL
- 4.1 PART Ⓐ (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :PHOSPHOR BRONZE
- 4.2 PART Ⓑ (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
: 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- Ⓒ NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l'recn nodr date	tolerances unless otherwise specified		MM	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3 0.XX±0.13 0'±2"	scale:5:1	dwg no 94721
	dr	c L FENG 04/06/94		sheet 6 of 12 size A4
	eng	JOSEPH HSIA 04/06/94		
	chr	JOSEPH HSIA 04/06/94		
	app	D K WANG 04/06/94		
sheet index	revision sheet			type Product Customer Drawing

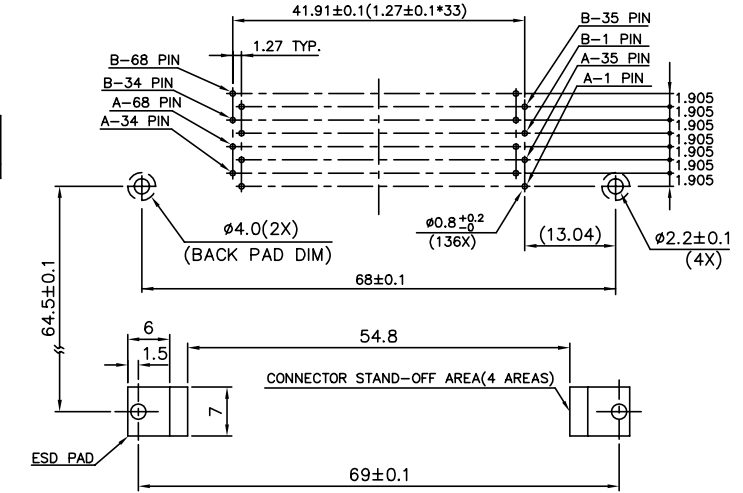
PRODUCT NO.
94721-105CA/105CALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
 - ASSY PROCESS
 - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
 - EJECT TRAVEL: 9.0mm
 - MATERIAL
 - PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :PHOSPHOR BRONZE
 - PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
 - FINISH (PIN)
UNDER PLATING :0.5µm MIN. Ni
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR *****LF)

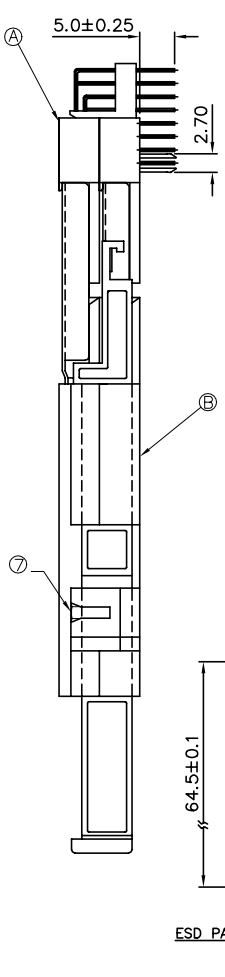
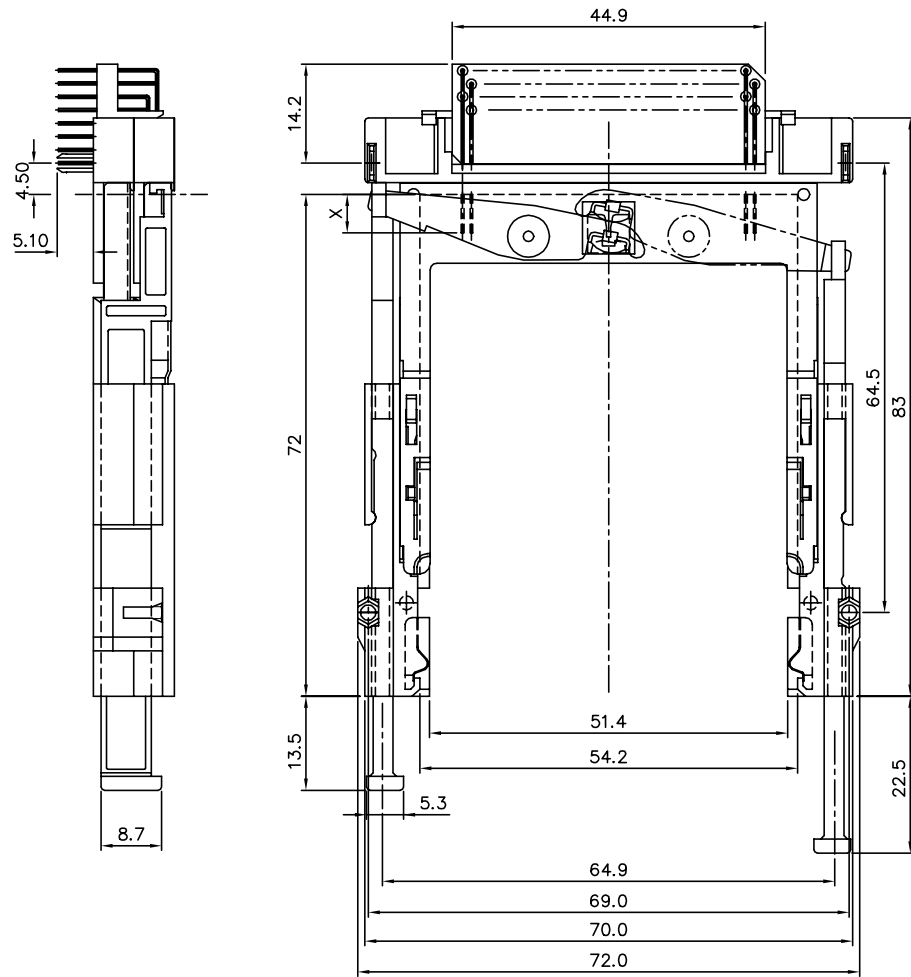
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
ISD1302	ISD406 ISD1101			PCMCIA
l trechn nodr date	tolerances unless otherwise specified			
M	angle	0.X±0.3	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
	0°±2'	0.XX±0.13	scale:1.5:1	
		0.XXX±0.05		
dr	c L FENG	04/06/94		dwg no
eng	JOSEPH HSIA	04/06/94		sheet 7 of 12
chr	JOSEPH HSIA	04/06/94		size
app	D K WANG	04/06/94		A4
sheet index	revision sheet			type Product Customer Drawing

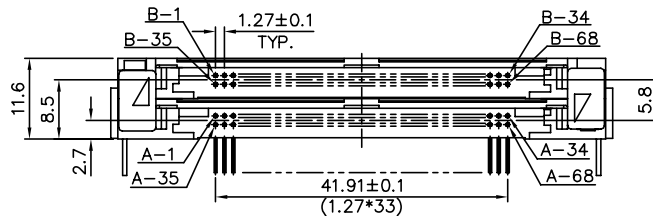
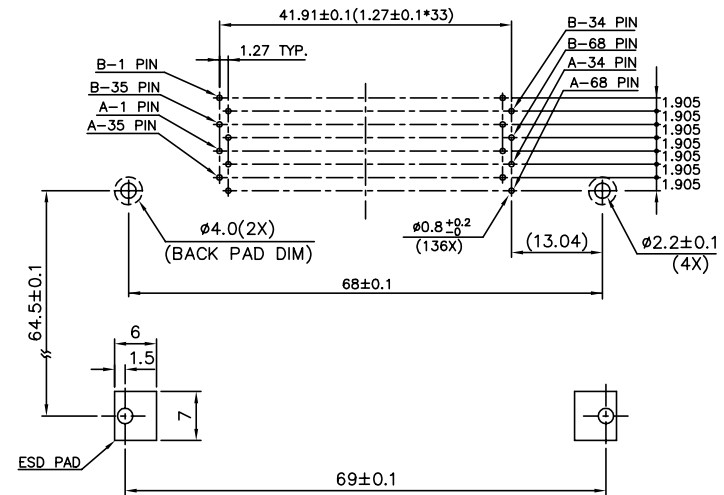
PRODUCT NO.
94721-003DA/003DALF



NOTES:

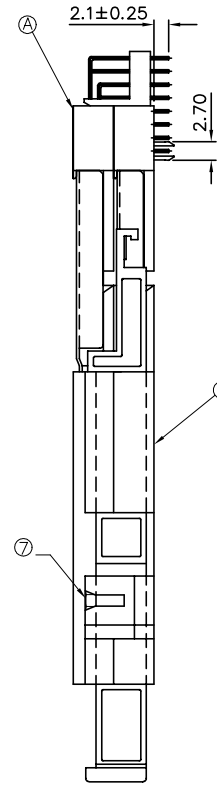
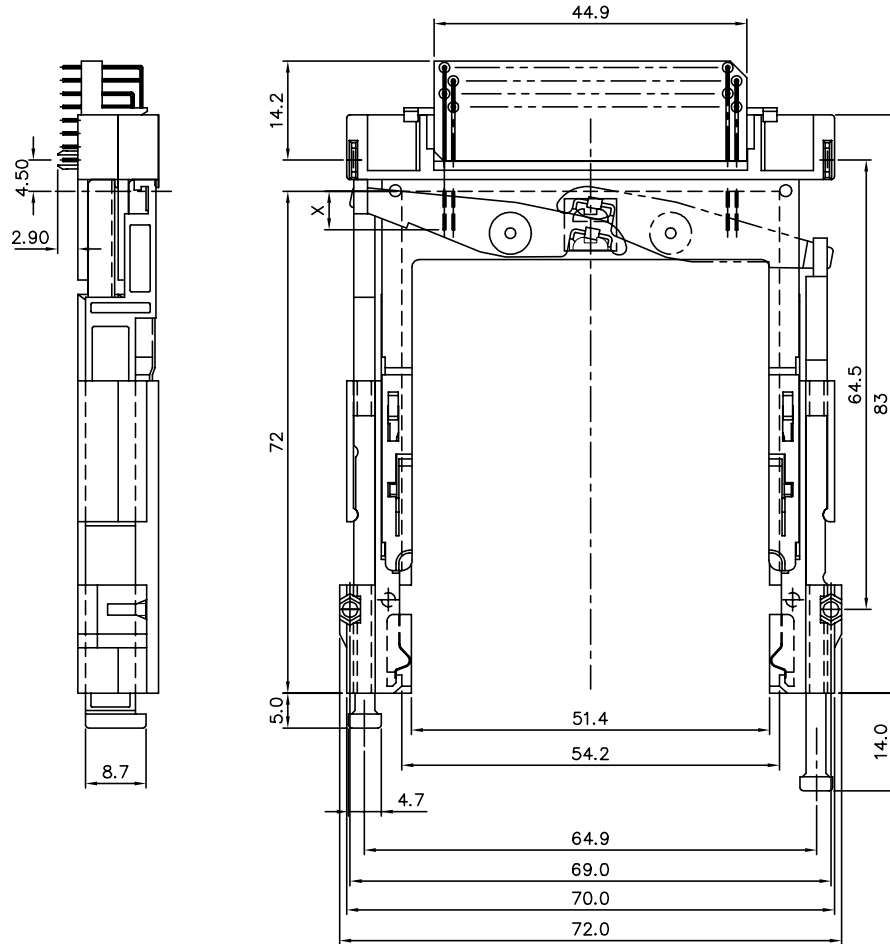
1. EJECT FORCE 3.5 Kg MAX.
2. ASSY PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. NI
 - CONTACT AREA : 0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l trechn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale: 5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 8 of 12 size A4
	dr c L FENG	0.XXX±0.05		type Product Customer Drawing
	engr JOSEPH HSIA	04/06/94		
	chr JOSEPH HSIA	04/06/94		
	appd D K WANG	04/06/94		
sheet index	revision sheet			

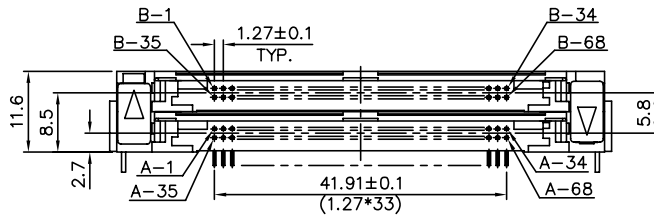
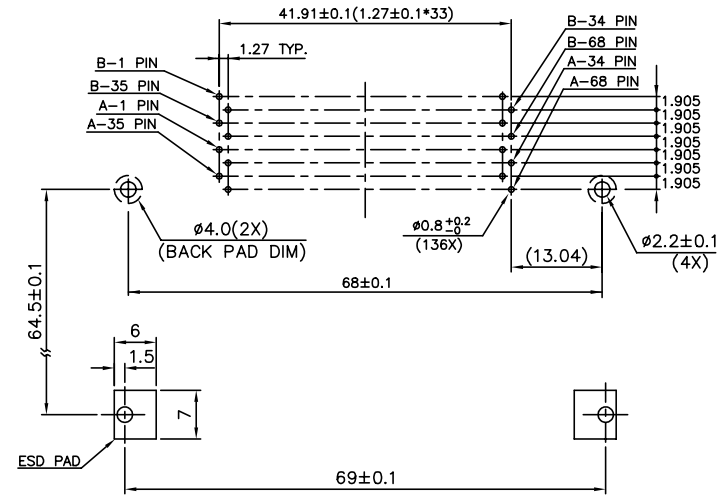
PRODUCT NO.
94721-005CA/005CALF



NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
- 4.1 PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
- 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



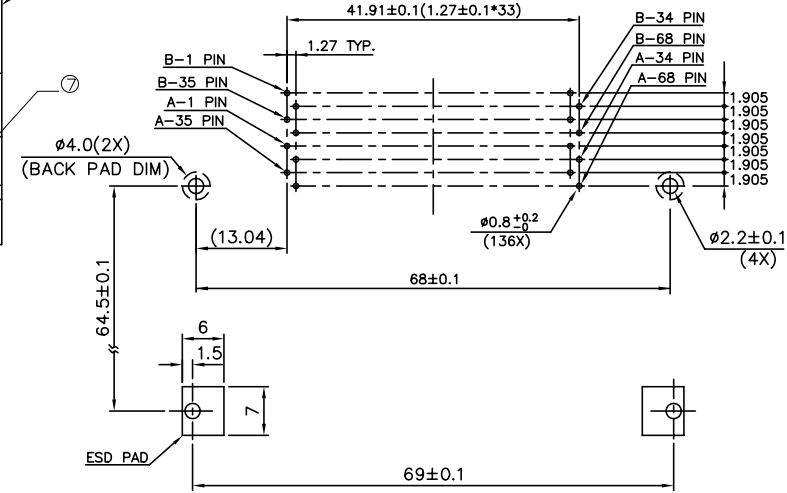
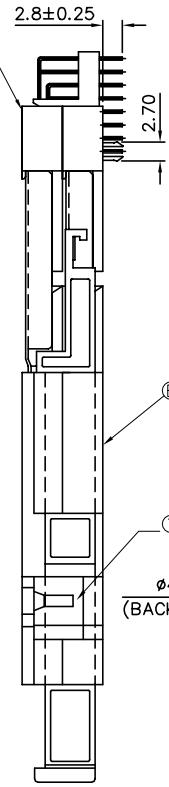
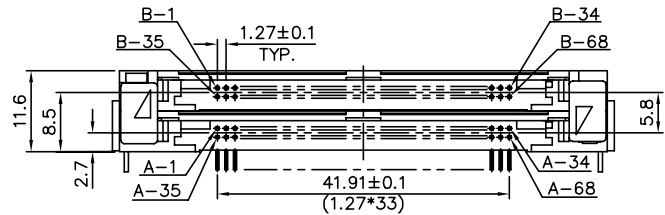
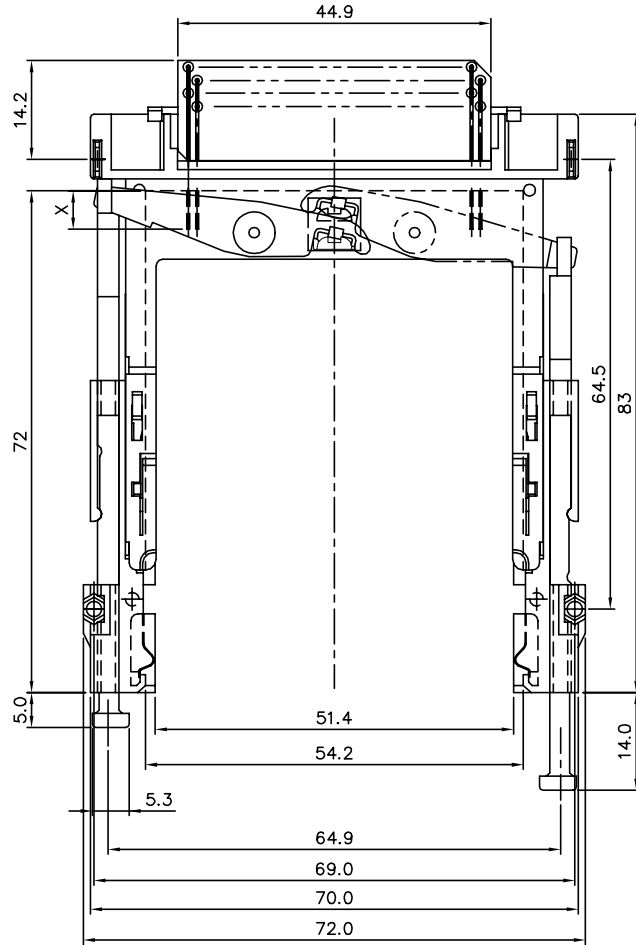
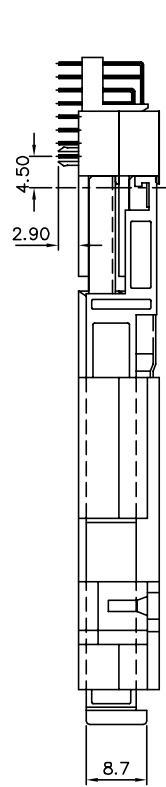
mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
ltr ecn nodr	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale: 5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 9 of 12 size A4
		0.XXX±0.05		type Product Customer Drawing
dr	c L FENG	04/06/94		
eng	JOSEPH HSIA	04/06/94		
chr	JOSEPH HSIA	04/06/94		
app	D K WANG	04/06/94		
sheet index	revision sheet			

PRODUCT NO.
94721-006CA/006CALF

1 | 2

3 |

4



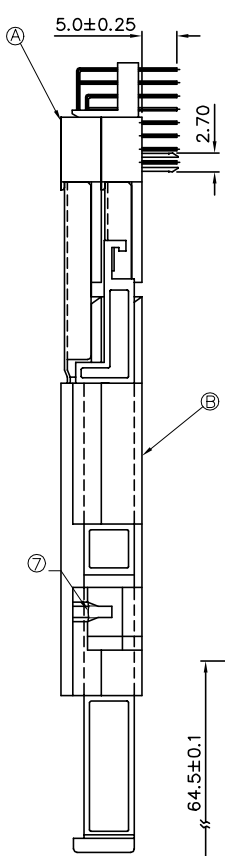
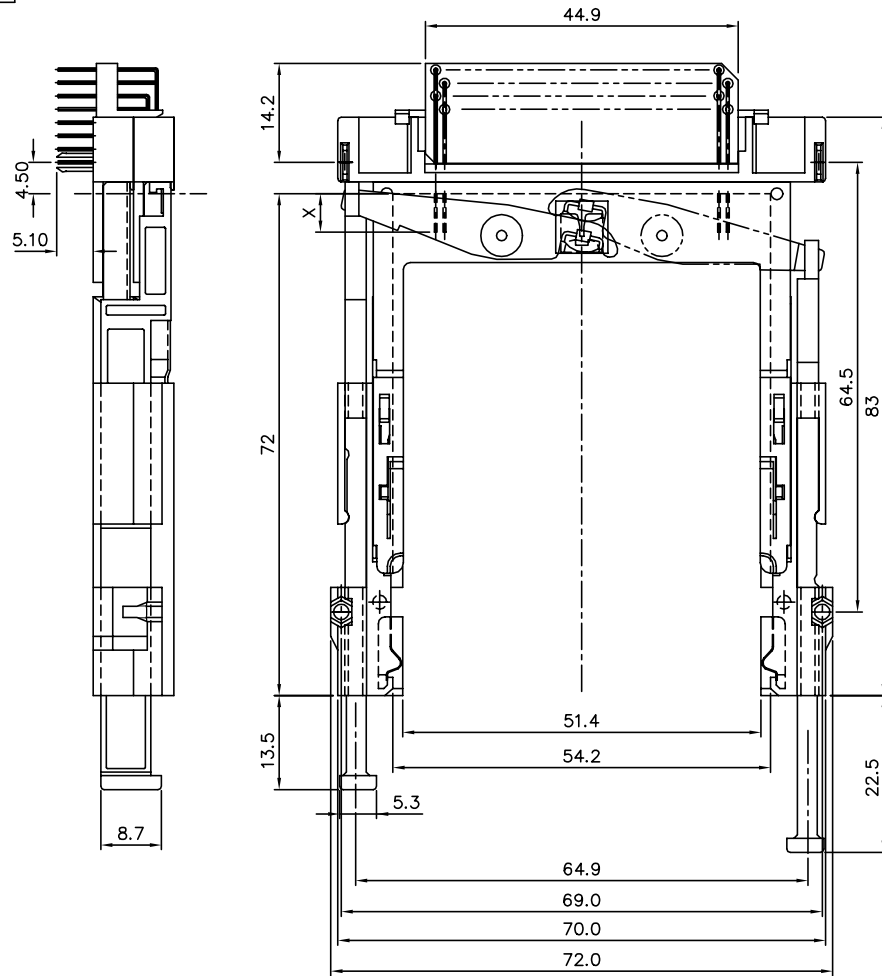
NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
 - 2.1 TO MOUNT PART ④ ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART ③ WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
- ④ MATERIAL
 - 4.1 PART ④ (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - 4.2 PART ③ (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. NI
 - CONTACT AREA :0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- ⑦ NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- B IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263

mat'l. code	surface	tolerance	projection	product family
ISD1302	ISD406	ISD1101	PCMCIA	
l t r e c n n o d r	date	tolerances unless otherwise specified	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M		angle	scale: 5:1	dwg no
		0°±2'		94721
	dr	c L FENG	04/06/94	sheet 10 of 12
	eng	JOSEPH HSIA	04/06/94	size
	chr	JOSEPH HSIA	04/06/94	A4
	app	D K WANG	04/06/94	type
sheet index	revision sheet			Product Customer Drawing

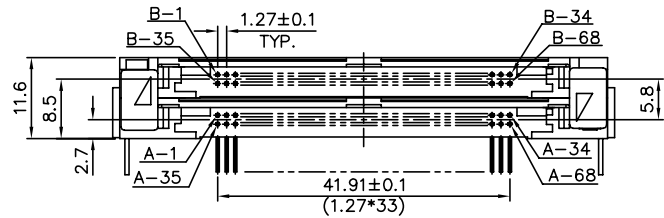
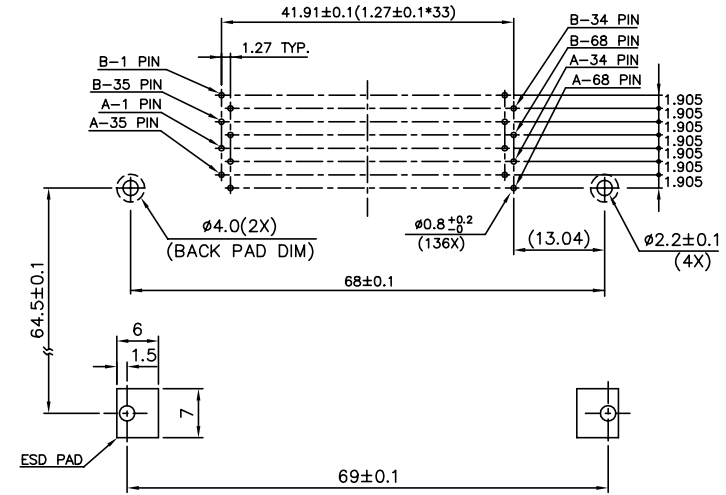
PRODUCT NO.
94721-004DA/004DALF



NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. NI
 - CONTACT AREA :0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302 ✓	tolerance ISO406 ISO1101	projection MM	product family PCMCIA
ltr ecn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle 0°±2'	0.X±0.3 0.XX±0.13 0.XXX±0.05	scale:1.5:1	sheet 11 of 12 size A4
dr	c L FENG	04/06/94		dwg no 94721
eng	JOSEPH HSIA	04/06/94		sheet 11 of 12 size A4
chr	JOSEPH HSIA	04/06/94		type Product Customer Drawing
app	D K WANG	04/06/94		
sheet index	revision sheet			

